

Special Issue

Editorial Board Members' Collection Series: Plasma Techniques

Message from the Guest Editor

We are pleased to announce this collection titled "Editorial Board Members' Collection Series: Plasma Techniques". This issue will be a collection of papers, and researchers invited by the Editorial Board Members. The aim is to provide a venue for networking and communication between *Applied Sciences* and scholars in the field of Plasma Techniques. All papers will be published with full open access after peer review.

Guest Editor

Dr. Heping Li

Department of Engineering Physics, Tsinghua University, Beijing 100084, China

Deadline for manuscript submissions

closed (20 April 2024)



Applied Sciences

an Open Access Journal
by MDPI

Impact Factor 2.5
CiteScore 5.5



mdpi.com/si/188601

Applied Sciences
Editorial Office
MDPI, Grosspeteranlage 5
4052 Basel, Switzerland
Tel: +41 61 683 77 34
appls-ci@mdpi.com

[mdpi.com/journal/
appls-ci](https://mdpi.com/journal/appls-ci)





Applied Sciences

an Open Access Journal
by MDPI

Impact Factor 2.5
CiteScore 5.5



[mdpi.com/journal/
applsci](https://mdpi.com/journal/applsci)



About the Journal

Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal *Applied Sciences* has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

Editor-in-Chief

Prof. Dr. Giulio Nicola Cerullo
Dipartimento di Fisica, Politecnico di Milano, Piazza L. da Vinci 32,
20133 Milano, Italy

Author Benefits

Open Access:

free for readers, with article processing charges (APC) paid by authors or their institutions.

High Visibility:

indexed within Scopus, SCIE (Web of Science), Ei Compendex, Inspec, CAPlus / SciFinder, and other databases.

Journal Rank:

JCR - Q2 (Engineering, Multidisciplinary) / CiteScore - Q1 (General Engineering)